

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Character	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	30	V		
Gate-Source Voltage			V _{GSS}	±25	V
Continuous Drain Current (Note 5) V _{GS} = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	5.3 4.2	А
Continuous Drain Current (Note 6) V _{GS} = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	8.0 6.3	А
Continuous Drain Current (Note 6) V _{GS} = 10V	t ≤ 10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	9.5 7.7	А
Continuous Drain Current (Note 6) V _{GS} = 4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	6.5 4.9	А
Continuous Drain Current (Note 6) V _{GS} = 4.5V	t ≤ 10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	7.8 6.2	Α
Pulsed Drain Current (Note 7)	I _{DM}	70	Α		
Avalanche Current (Notes 7 & 8)	I _{AR}	18	Α		
Repetitive Avalanche Energy (Notes 7 & 8) L = 0.1mH			E _{AR}	16	mJ

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 5)	P_{D}	1.0	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	$R_{\theta JA}$	130.6	°C/W
Power Dissipation (Note 6)	P _D	2.07	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 6)	$R_{\theta JA}$	62.5	°C/W
Power Dissipation (Note 6) t ≤ 10s	P_{D}	3.0	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 6) t ≤ 10s	$R_{\theta JA}$	43.8	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes:

- 5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
 6. Device mounted on 2" x 2" FR-4 PCB with high coverage 2 oz. Copper, single sided.
 7. Repetitive rating, pulse width limited by junction temperature.

- 8. I_{AR} and E_{AR} rating are based on low frequency and duty cycles to keep T_J = +25°C.

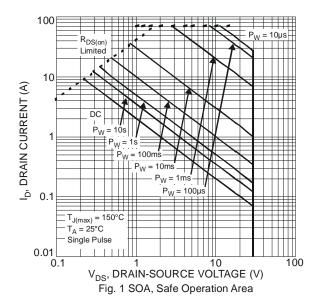


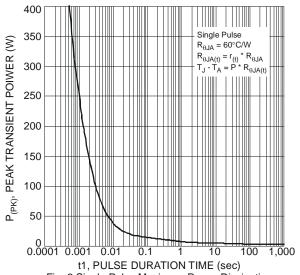
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	-	0.1	μΑ	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 25V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(th)}	0.8	1.2	2.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance		-	13.5	20	mΩ	$V_{GS} = 10V, I_D = 10A$	
Static Drain-Source On-Resistance	R _{DS (ON)}	-	22	27		$V_{GS} = 4.5V, I_D = 7.5A$	
Forward Transfer Admittance	Y _{fs}	-	13.0	-	S	$V_{DS} = 5V, I_{D} = 10A$	
Diode Forward Voltage	V_{SD}	-	0.7	1.0	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C _{iss}	-	580	-		451/11/	
Output Capacitance	Coss	-	110	-	pF	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C_{rss}	-	70	-			
Gate Resistance	R_g	-	2.0	3.0	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge V _{GS} = 4.5V	Q_{g}	-	5.3	-	$V_{GS} = 4.5V, V_{DS} = 15V, I_D =$		
Total Gate Charge V _{GS} = 10V	Q_g	-	11.3	-	nC	$V_{GS} = 10V, V_{DS} = 15V,$ $I_{D} = 10A$	
Gate-Source Charge	Q_{gs}	-	1.9	-	IIC		
Gate-Drain Charge	Q_{gd}	-	1.9	-			
Turn-On Delay Time	t _{D(on)}	-	4.4	-	ns		
Turn-On Rise Time	tr	-	4.6	-	ns	V _{GS} = 10V, V _{DS} = 15V,	
Turn-Off Delay Time	t _{D(off)}	-	19.5	-	ns	$R_L = 15\Omega$, $R_G = 6\Omega$	
Turn-Off Fall Time	t _f	-	5.8	-	ns	ıs	
Bodyy Diode Reverse Recovery Time	t _{rr}	-	12.6	-	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	=	10.5	-	nC		

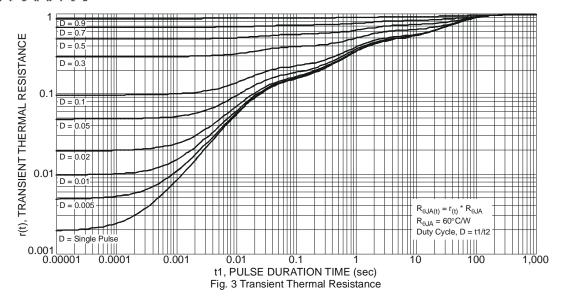
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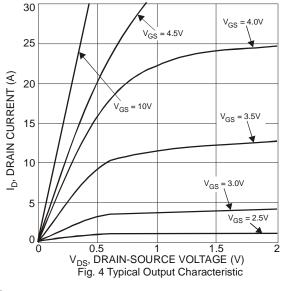
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to production testing.

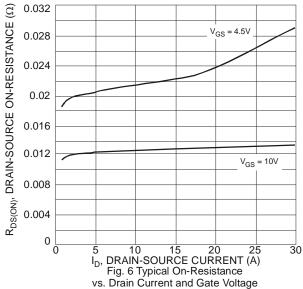


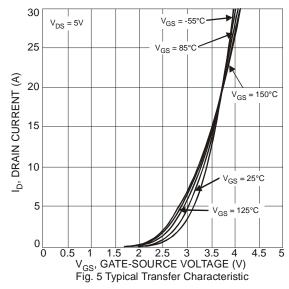


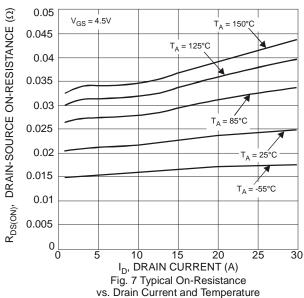




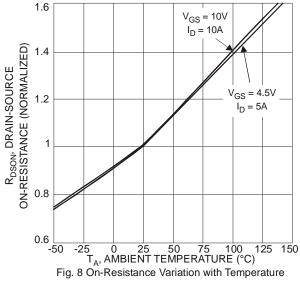


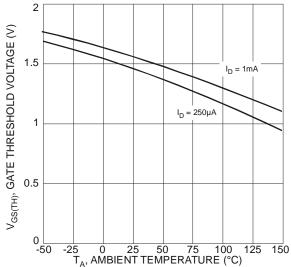


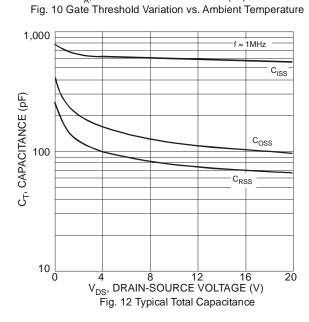


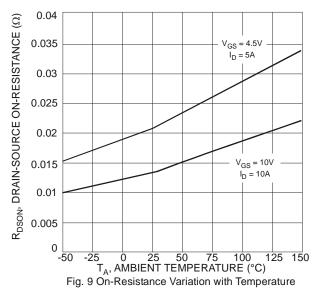


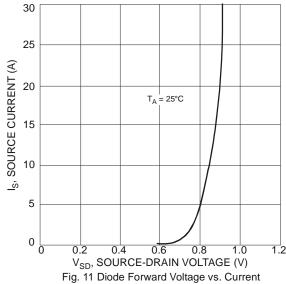


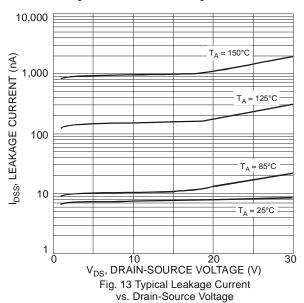










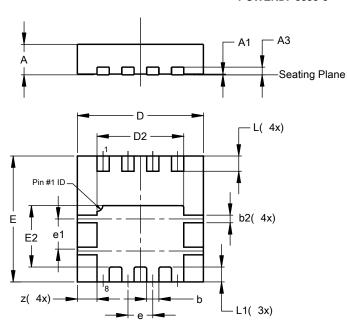




Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

POWERDI®3333-8

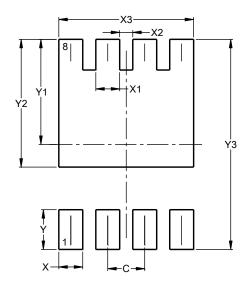


POWERDI®3333-8						
Dim	Min	Max	Тур			
Α	0.75	0.85	0.80			
A1	0.00	0.05	0.02			
A3	_	_	0.203			
b	0.27	0.37	0.32			
b2	_	_	0.20			
D	3.25	3.35	3.30			
D2	2.22	2.32	2.27			
E	3.25	3.35	3.30			
E2	1.56	1.66	1.61			
е	_	_	0.65			
e1	0.79	0.89	0.84			
L	0.35	0.45	0.40			
L1	_	_	0.39			
Z	_	_	0.515			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

POWERDI®3333-8



Dimensions	Value (in mm)		
С	0.650		
Х	0.420		
X1	0.420		
X2	0.230		
Х3	2.370		
Y	0.700		
Y1	1.850		
Y2	2.250		
Y3	3.700		



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